Huan Yu

List of Publications by Year
in descending order

12	193	1307594 7	1720034 7
papers	citations	h-index	g-index

12	12	12	187
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Demystifying Machine Learning for Signal and Power Integrity Problems in Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1276-1295.	2.5	48
2	An ultra-low-cost electroporator with microneedle electrodes (ePatch) for SARS-CoV-2 vaccination. Proceedings of the National Academy of Sciences of the United States of America, 2021, 118, .	7.1	38
3	Surface Roughness Modeling of Substrate Integrated Waveguide in D-Band. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 1209-1216.	4.6	27
4	Modeling of Voltage-Controlled Oscillators Including I/O Behavior Using Augmented Neural Networks. IEEE Access, 2019, 7, 38973-38982.	4.2	19
5	Repeater Insertion to Reduce Delay and Power in Copper and Carbon Nanotube-Based Nanointerconnects. IEEE Access, 2019, 7, 13622-13633.	4.2	16
6	Behavioral Modeling of Tunable I/O Drivers With Preemphasis Including Power Supply Noise. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2020, 28, 233-242.	3.1	14
7	Dynamic Thermal Management for 3-D ICs With Time-Dependent Power Map Using Microchannel Cooling and Machine Learning. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1244-1252.	2.5	12
8	Preliminary application of machine-learning techniques for thermal-electrical parameter optimization in 3-D IC. , 2016, , .		8
9	Invertible Neural Networks for Inverse Design of CTLE in High-speed Channels. , 2020, , .		8
10	Behavioral Modeling of Pre-emphasis Drivers Including Power Supply Noise Using Neural Networks. , 2019, , .		2
11	Machine Learning for 3D-IC Electric-Thermal Simulation and Management. , 2018, , .		1
12	A Bit-Time-Dependent Model of I/O Drivers for Overclocking Analysis. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2020, 28, 1630-1637.	3.1	0